



Connectors > Socket Connectors > Memory Sockets > DIMM Sockets



DRAM Type: **Double Data Rate (DDR) 2**

Connector System: **Board-to-Board**

Number of Positions: **240**

Module Orientation: **25°**

Centerline (Pitch): **1 mm [ .039 in ]**

## Features

### Product Type Features

DRAM Type	Double Data Rate (DDR) 2
Connector System	Board-to-Board
Connector & Contact Terminates To	Printed Circuit Board

### Configuration Features

Number of Bays	2
Number of Keys	1
Number of Rows	2
Number of Positions	240
Module Orientation	25°

### Electrical Characteristics

DRAM Voltage	1.8 V
--------------	-------

### Body Features

PCB Retention Feature Material	Copper Alloy
Ejector Material Color	Natural
Ejector Material	High Temperature Thermoplastic
Latch Color	Natural
Ejector Location	Both Ends
Latch Material	High Temperature Thermoplastic
Retention Post Location	Both Ends
Module Key Type	Center

Connector Profile	Low
-------------------	-----

Ejector Type	Standard
--------------	----------

### Contact Features

Memory Socket Type	Memory Card
--------------------	-------------

Socket Style	DIMM
--------------	------

PCB Contact Termination Area Plating Material Thickness	3 $\mu\text{m}$ [118.1 $\mu\text{in}$ ]
---	---

Contact Mating Area Plating Material Thickness	.76 $\mu\text{m}$ [30 $\mu\text{in}$ ]
--	--

Contact Mating Area Plating Material	Gold
--------------------------------------	------

Contact Underplating Material	Nickel
-------------------------------	--------

PCB Contact Termination Area Plating Material	Tin
---	-----

Contact Base Material	Copper Alloy
-----------------------	--------------

Contact Current Rating (Max)	.5 A
------------------------------	------

### Termination Features

Insertion Style	Direct Insert
-----------------	---------------

Termination Post & Tail Length	4 mm[.157 in]
--------------------------------	---------------

### Mechanical Attachment

Mating Alignment Type	Center
-----------------------	--------

Mating Alignment	With
------------------	------

Mount Angle	Right Angle
-------------	-------------

PCB Mount Retention	With
---------------------	------

PCB Mount Retention Type	Boardlock
--------------------------	-----------

Connector Mounting Type	Board Mount
-------------------------	-------------

### Housing Features

Housing Material	High Temperature Thermoplastic
------------------	--------------------------------

Housing Color	Black
---------------	-------

Centerline (Pitch)	1 mm[.039 in]
--------------------	---------------

### Dimensions

Center Retention Hole Diameter	1.8 x 2.45 mm, 1.8 mm[.07 in]
--------------------------------	-------------------------------

Profile Height from PCB	16.2 mm[.63 in]
-------------------------	-----------------

Row-to-Row Spacing	1.9 mm[.075 in]
--------------------	-----------------

### Usage Conditions

Operating Temperature Range	-55 – 105 $^{\circ}\text{C}$ [-67 – 221 $^{\circ}\text{F}$ ]
-----------------------------	--

### Operation/Application

Circuit Application	Signal
---------------------	--------

### Industry Standards

UL Flammability Rating	UL 94V-0
------------------------	----------

### Packaging Features

Packaging Quantity	32
Packaging Method	Box & Tray, Tray

### Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JUN 2018 (191) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Wave solder capable to 240°C

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

### Documents

#### Product Drawings

[ASSY, 0.00076MIN AU 4.00 TAIL](#)

English

#### CAD Files



### 3D PDF

3D

Customer View Model

[ENG\\_CVM\\_CVM\\_1658912-3\\_B.2d\\_dxf.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_1658912-3\\_B.3d\\_igs.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_1658912-3\\_B.3d\\_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

### Product Specifications

[Application Specification](#)

English

### Product Environmental Compliance

[TE Material Declaration](#)

English